

Flip-Top™ BGA Sockets

Flip-Top™ BGA Sockets 1.27mm and 1.00mm Pitch

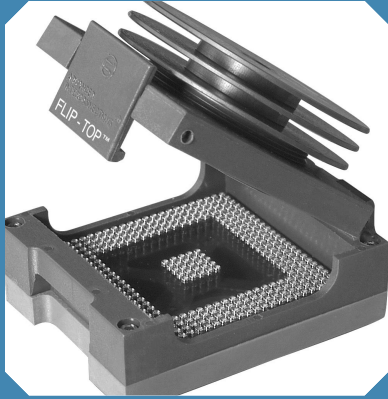
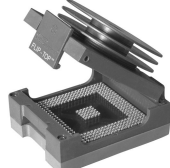
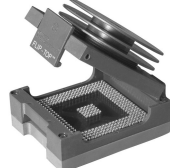


Table of Models

	<p>Description: Socket (FRG, 1.27mm pitch) Mat'l: High Temp. Liquid Crystal Polymer (LCP) Index: -40°C to 260°C (-40°F to 500°F)</p>	<p>Socket Size: 3.00mm wider and 10.00mm longer than BGA device (for packages larger than 15.00mm square).*</p>
	<p>Description: Socket (FRH, 1.00mm pitch) Mat'l: Thermoset Plastic Index: Consult Factory</p>	<p>Socket Size: 3.00mm wider and 10.00mm longer than BGA device (for packages larger than 15.00mm square).*</p>

Features:

- Designed to save space on new and existing PC boards in test, development, programming and production applications.
- No external hold-downs or soldering of BGA device required.
- AIC exclusive solder ball terminals offer superior processing.
- Uses same footprint as BGA device.
- Available with integral, finned heat sink or coin screw clamp assembly.

Specifications:

Terminals:

Brass - Copper Alloy
(C36000) ASTM-B-16

Contacts:

Beryllium Copper
(C17200) ASTM-B-194

Plating:

G - Gold over Nickel

Terminal Support:

Polyimide Film (FRG only)

Spring Material:

Stainless Steel

Heat Sink/Coin Screw and Support Plate Material:

Aluminum

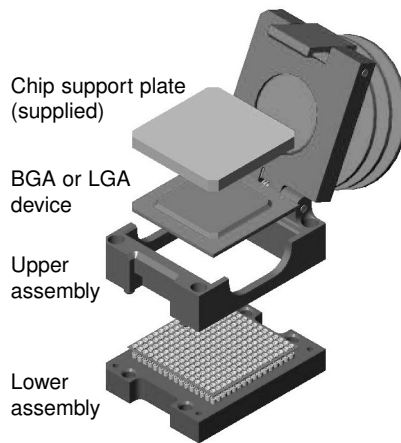
Solder Ball:

Standard: 63Sn/37Pb
 Lead-free: 95.5Sn/4.0Ag/0.5Cu

FRG replaces FTG.

* For device packages smaller than 15.00mm square, the socket size is $X = .709/(18.00)$ and $Y = .984/(25.00)$.

How It Works



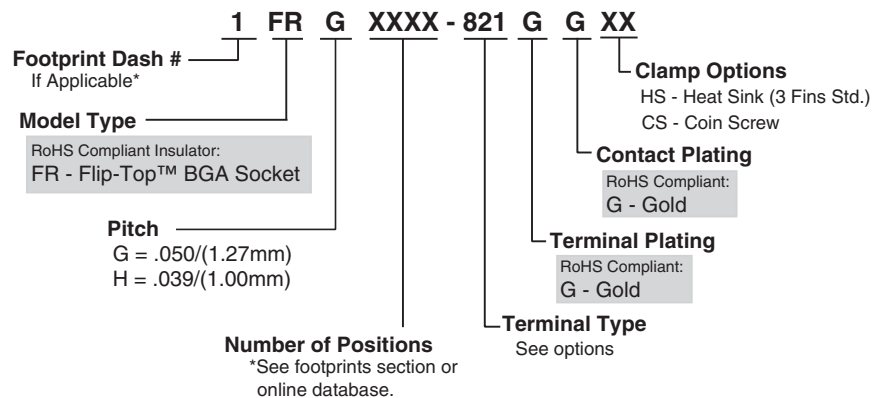
SMT models are shipped un-assembled to ease solderability. Thru-hole models are shipped fully assembled.

1. Lower assembly is soldered to PC board with no external hold-down mechanism. Thru-hole models may be soldered to PC board or plugged into a mating socket.
2. Upper assembly inserts easily to lower assembly by aligning guide posts and installing four (supplied) screws.
3. Finned heat sink or coin screw is screwed down to flush position.
4. Lid opens easily by pressing latch.
5. BGA device is inserted by aligning A1 position with chamfered corner of Flip-Top™ socket. Place support plate on top of device, close lid, engage heat sink or coin screw, and socket is ready for use.

See page 15 for Generic Reflow Profiles.

Detailed Installation and General Usage Instructions are provided with product.

How To Order



5 Energy Way, West Warwick, RI 02893 USA
 Tel: 800.424.9850 | 401.823.5200
 Fax: 401.823.8723
 info@advanced.com | www.advanced.com
 Catalog 16 rev. Sept. 07

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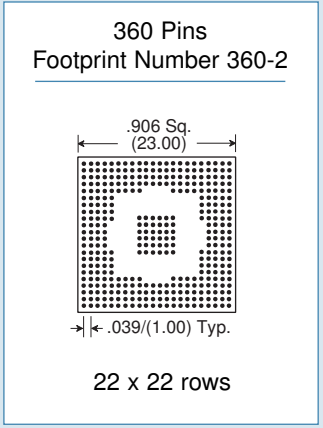


Terminals (for test, development and production applications)	
Tin/Lead: Type -690 Lead-free: Type -821 1.27mm pitch	Tin/Lead: Type -752 Lead-free: Type -837 1.00mm pitch
<p>SMT (Surface Mount)</p>	
<p>Thru-Hole</p>	

Terminals (for LGA or de-balled BGA device applications)	
Tin/Lead: Type -713 Lead-free: Type -822 1.27mm pitch	Tin/Lead: Type -762 Lead-free: Type -838 1.00mm pitch
<p>SMT (Surface Mount)</p>	
<p>Thru-Hole</p>	

Terminals (for BGA device test applications)	
Tin/Lead: Type -659 Lead-free: Type -820 1.27mm pitch	Tin/Lead: Type -TBD Lead-free: Type -TBD 1.00mm pitch
<p>SMT (Surface Mount)</p>	<p>Consult Factory</p>
<p>Thru-Hole</p> <p>Available with .016(0.41mm) Diam. tail; Type -709</p>	<p>Consult Factory</p>

Footprints:



- Full grid molded insulators populated to exact device pattern.
- Over 1000 footprints available - see page 99, search online or submit your device specs.
- Use our Build-A-Part feature or search in our online BGA Socket Finder™ at www.bgasockets.com.

Available Online:

- RoHS Qualification Test Report
- Technical articles
- Test data
- Signal Integrity Performance
- CAD drawings
- BGA Footprints



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